1 Characteristics

Table 1.	Absolute ratings	(limiting values)
	Aboolato latingo	(mining value)

Symbol	Parameter	Value	Unit
Тј	Maximum junction temperature	125	°C
T _{op}	Operating temperature range	-40 to +85	°C
T _{stg}	Storage temperature range	-55 to 150	°C

Table 2.

2. Electrical characteristics (T_{amb} = 25 °C)

Symbol	Parameters		I.		
V _{BR}	Breakdown voltage	T I			
I _{RM}	Leakage current @ V _{RM}	le			
V _{RM}	Stand-off voltage				
V _{CL}	Clamping voltage			→ V	
R _d	Dynamic impedance			V	
I _{PP}	Peak pulse current				
R _{I/O}	Series resistance between input and output			PP	
C _{line}	Input capacitance per line	1	I		
Symbol	Test conditions	Min	Тур	Мах	Unit
V_{BR}	I _R = 1 mA	6			V
I _{RM}	V _{RM} = 3 V per line			1	μA
R _d			1.5		Ω
R ₁		95	100	105	Ω
R ₂		44.65	47	49.35	Ω
R ₃		95	100	105	Ω
C _{line}	@ 0 V			35	pF

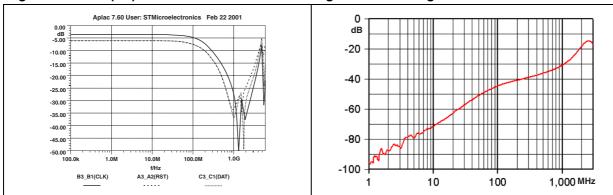
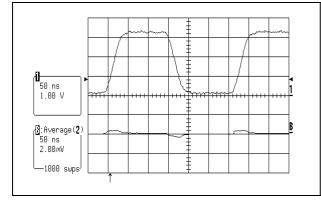






Figure 6. ESD response to IEC 61000-4-2 (-15 kV air discharge) on one input (Vin) and on one output (Vout)



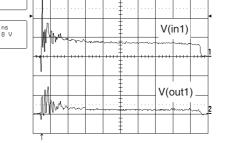
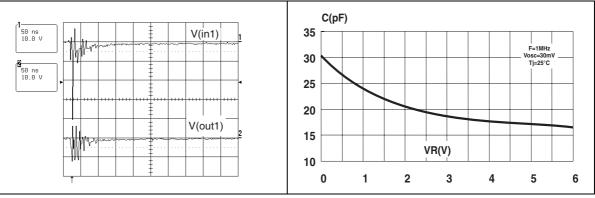


Figure 7. ESD response to IEC 61000-4-2 (+15 kV air discharge) on one input (Vin) and on one output (Vout)

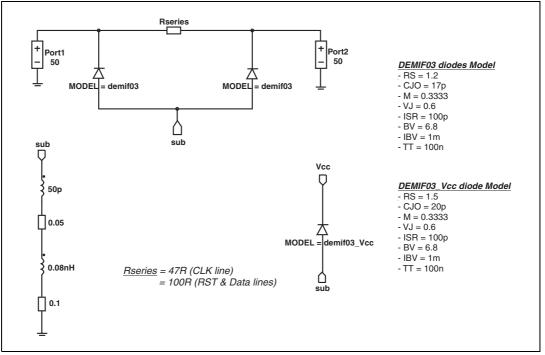
Figure 8. Line capacitance versus applied voltage (typical)





2 Application information





3 Ordering information scheme

Figure 10. Ordering information scheme

	EMIF	уу	-	ххх	ZZ	Fx
EMI Filter						
Number of lines						
Information						
x = resistance value (Ohms)						
z = capacitance value / 10(pF)						
or						
3 letters = application						
2 digits = version						
Package						
F = Flip Chip						
x = 2: Lead-free, pitch = 500 μ m, bump = 315 μ	Im					



4 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at *www.st.com*.



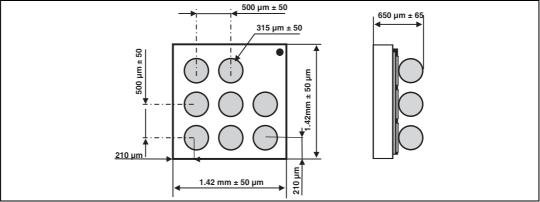


Figure 12. Footprint

Figure 13. Marking

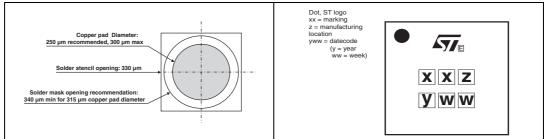
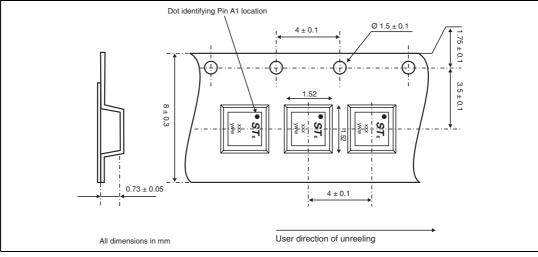


Figure 14. Flip Chip tape and reel specification





5 Ordering information

Table 3.Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF03-SIM01F2	FC	Flip Chip	2.9 mg	5000	Tape and reel 7"

Note:

More information is available in the application notes: AN1235:"Flip Chip: Package description and recommendations for use" AN1751: "EMI filters: Recommendations and measurements"

6 Revision history

Date	Revision	Changes
08-Oct-2004	1	Initial release.
13-Dec-2004	2	Table 3. on page 6: Flip Chip weight corrected from 3.3 mg to 2.9 mg.
28-Apr-2008	3	Updated ECOPACK statement. Updated <i>Figure 10</i> , <i>Figure 11</i> and <i>Figure 14</i> . Reformatted to current standards.

Table 4.Document revision history

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